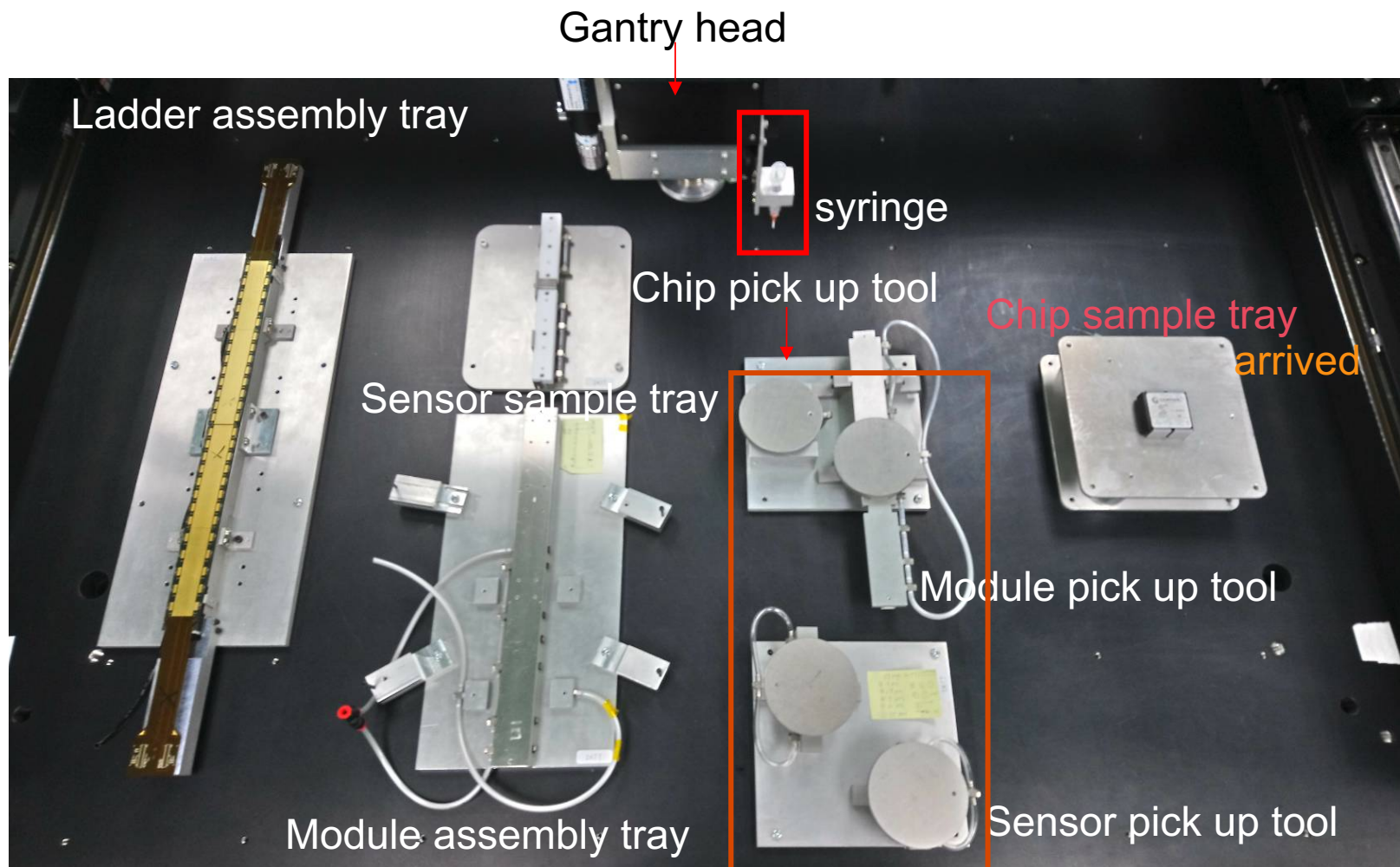


sPHENIX INTT

Cheng-Wei Shih, Kai-Yu Cheng, Chia-Ming Kuo, Hung-Yu (NCU)
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Takahito Todoroki, Itaru Nakagawa (RBRC)
Takashi Hachiya, Ayaka Suzuki, Miu Morita, Mika Shibata (NWU)
Donald Pinelli, Rachid Nouicer (BNL)
Rui Xiao (PURDUE)



Assembly family status



Pick up tool upgrade



Chip pick up tools upgrade



Alignment list :

Chip : diagonal corners

HDI : cross marks

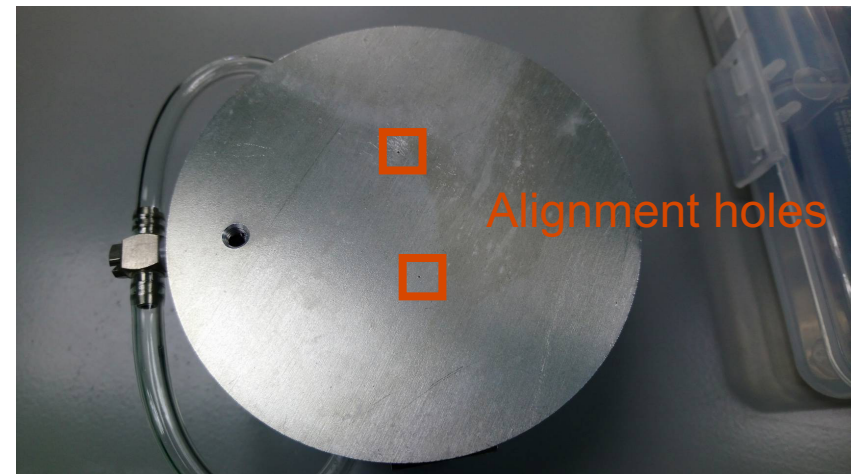
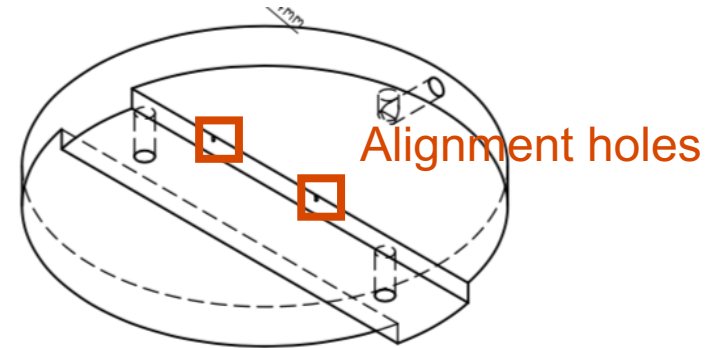
Pick up tool : two alignment holes

Sensor : cross marks

Sensor Type B cross mark distance

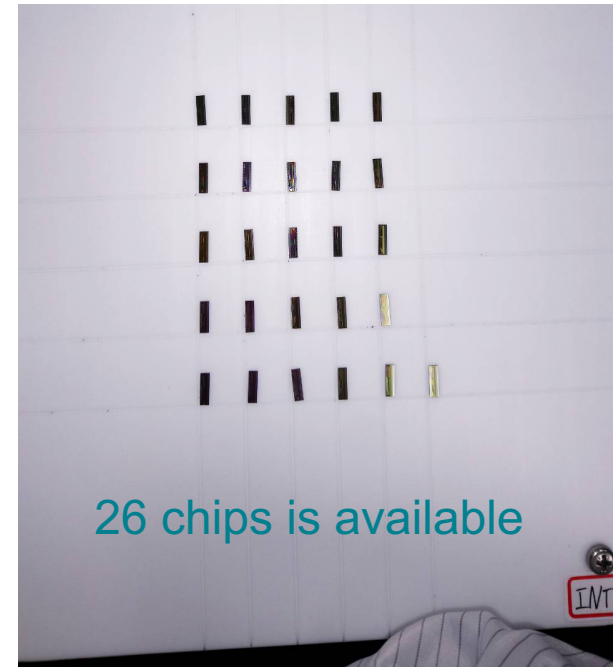
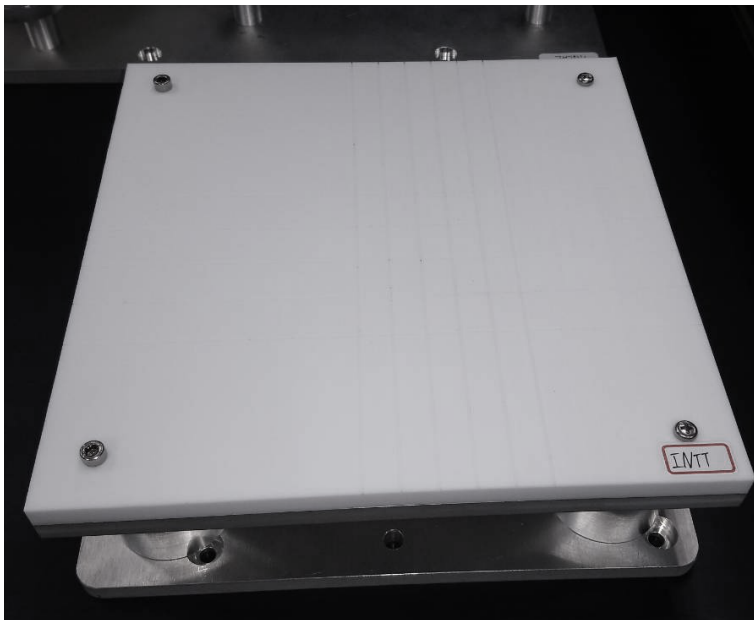
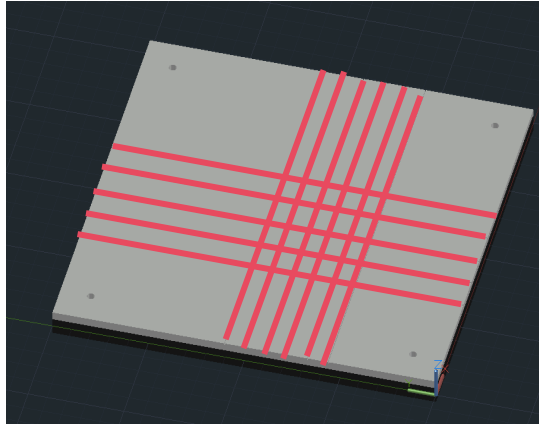
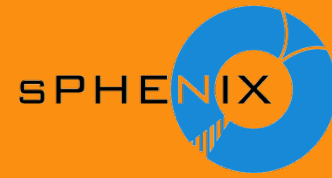
X : 101.5 mm

Y : 22 mm (measured by OGP)



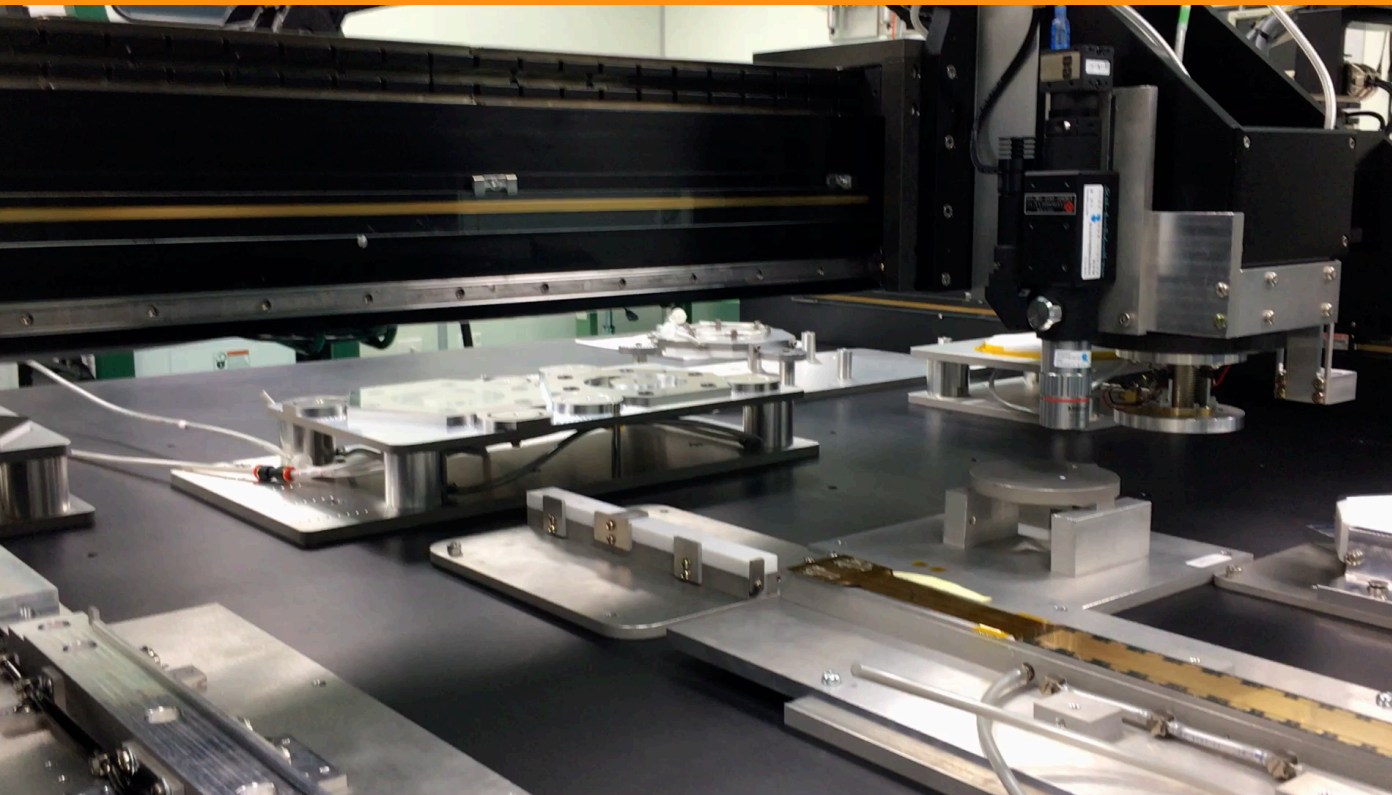


Assembly family status - chip sample tray



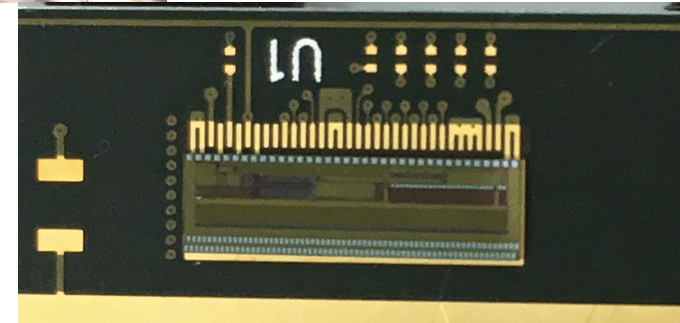


INTT assembly status



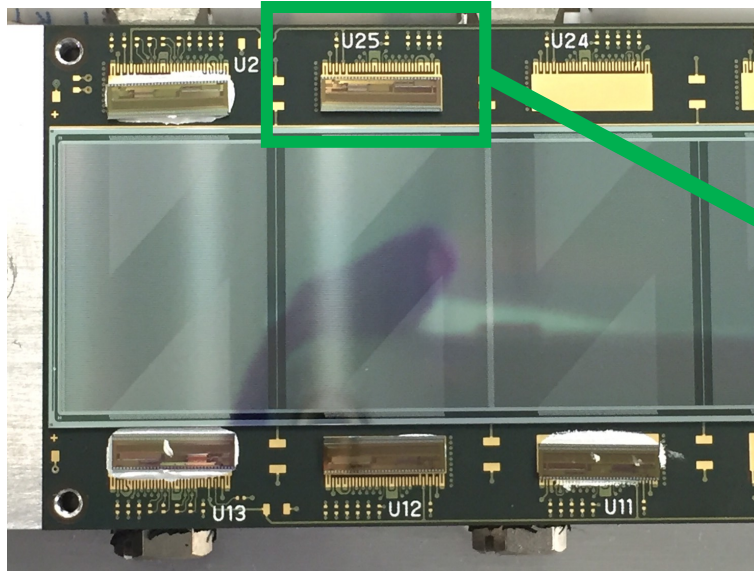
Chip assembly test

Tested without glue



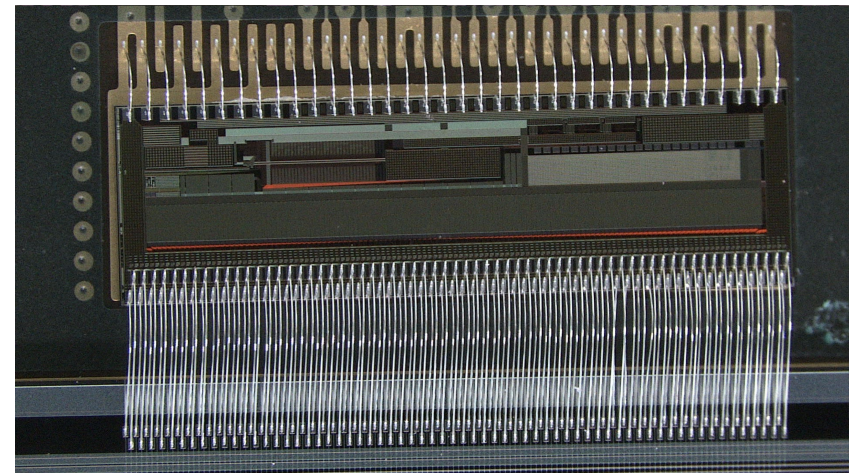


NCU bonding performance



Bonding in NTU

Bonding test



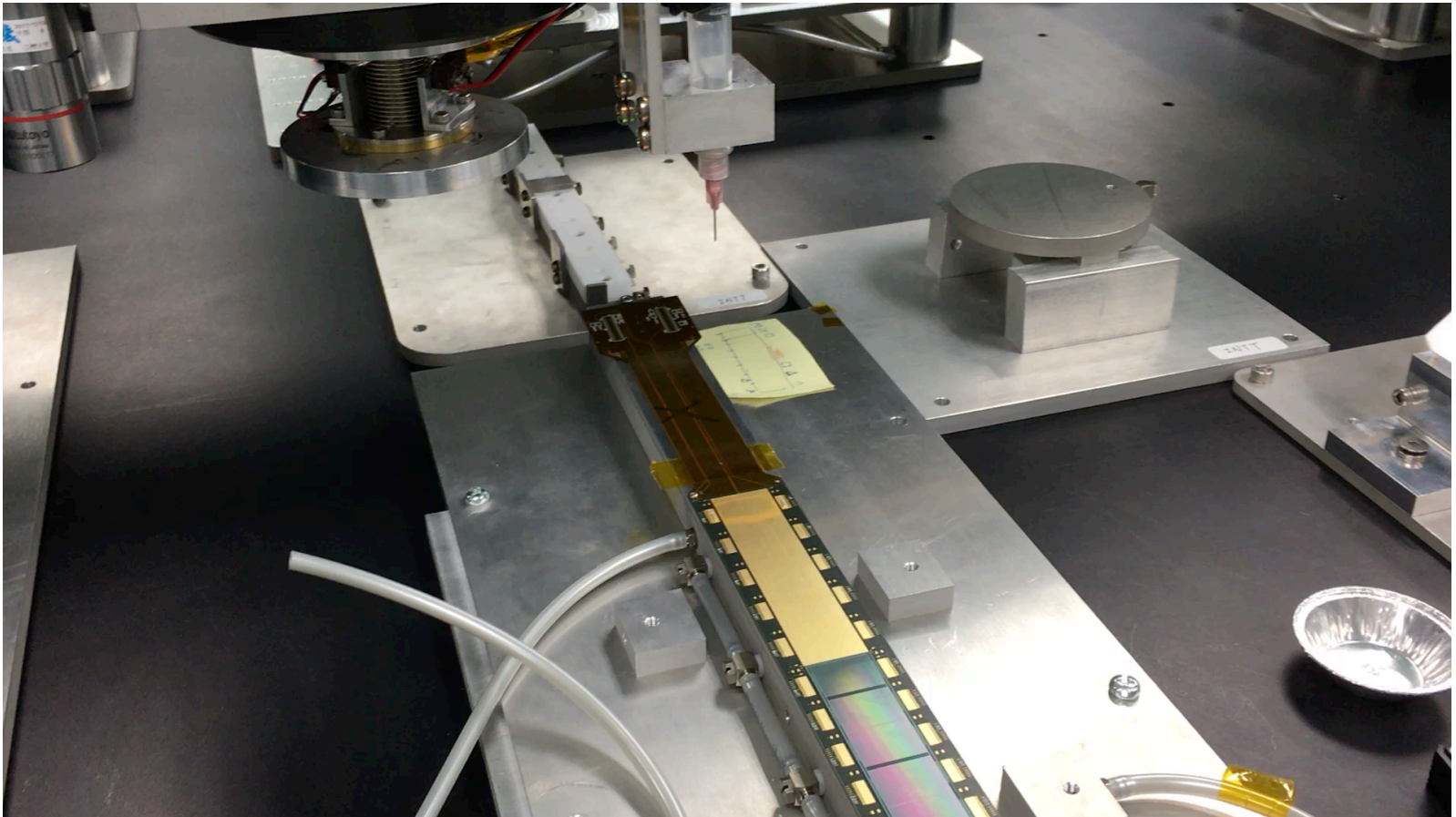
To test the property, put the chips by hand, glue is applied by glue mask



Glue test



Start from 16 sec

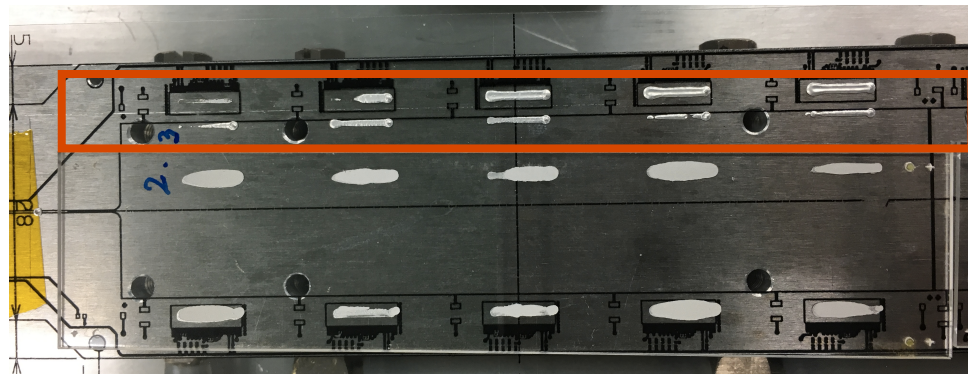




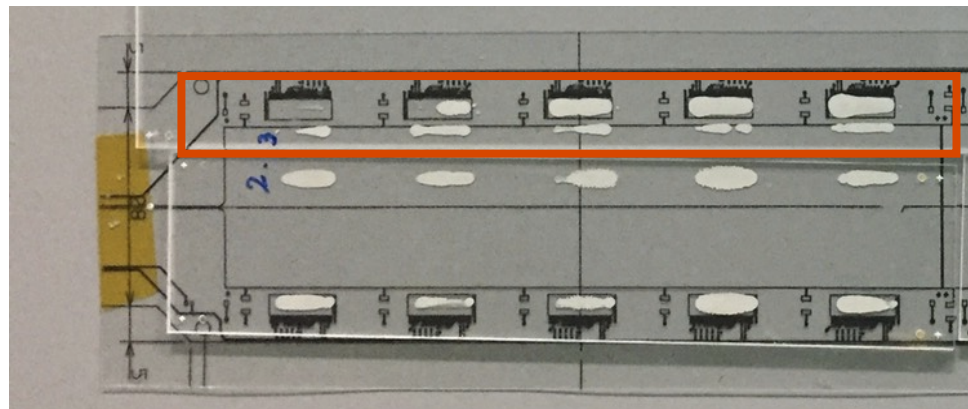
Glue test

The glue dragging problem solved

Several parameters are tested:
pressure,
waiting time,
applying length,
Diameter of syringe tube



Before



after



Glue test

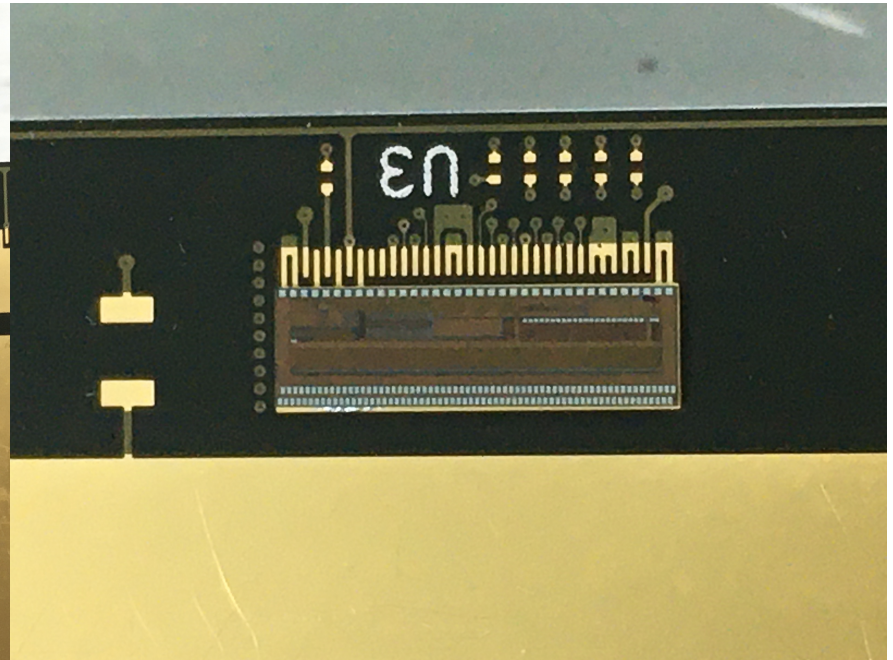


First good assembly

Before



After



After mix, wait for 30 mins. To have the glue viscosity higher



Test Bench problem



- Plan : Having two Test Bench system in Taiwan (one in NCU, one in NTU)
- Problem : The one FEM-IB can not work so far.
- Solution : Is it possible to be fixed ?
Produce a new one possible ?

Name	Request	In NCU
ROC	1	2
BCO/Start board	1	2
FEM	1	3
FEM - IB	1	1
VME crate	1	2
PCIe board	1	1 (can be purchased)

The necessary components



To do list



- This week :
 - Assemble and bond 10 good chips on real HDI in NTU
- Next week :
 - Take the calibration with this “semi - half module” in NCU.
 - Assemble the sensor type B on ”semi - half module” in NTU if all chips are good.
- Week 5/4 :
 - Take the calibration with this “half module” in NCU.
- If it is tested to be good, start the type A part assembly.



Schedule



- ~~Set up Test Bench in NCU.~~
- ~~Solve the glue dragging problem when using syringe to apply glue~~
- Test encapsulation.
- ~~Check the bonding performance with OGP~~
- Try to make a functional module in Taiwan.

Back up



INTT assembly family



Name	amount	Status
Ladder assembly tray	1	In NTU
Module assembly tray	1	In NTU
HDI handle	3	3 In NTU
Chip sample tray	1	1 in NTU
Sensor sample tray	1	In NTU
Chip pick up tool	1	In NTU
Sensor pick up tool	2 sets (1 set : type A and B)	In NTU
Module pick up tool	1	In NTU
Glue mask	2 sets (1 set :1 for sensor, 1 for chips)	2 In NTU
Shipping box	1	Designing

Summary : all the prototype tools are arrived

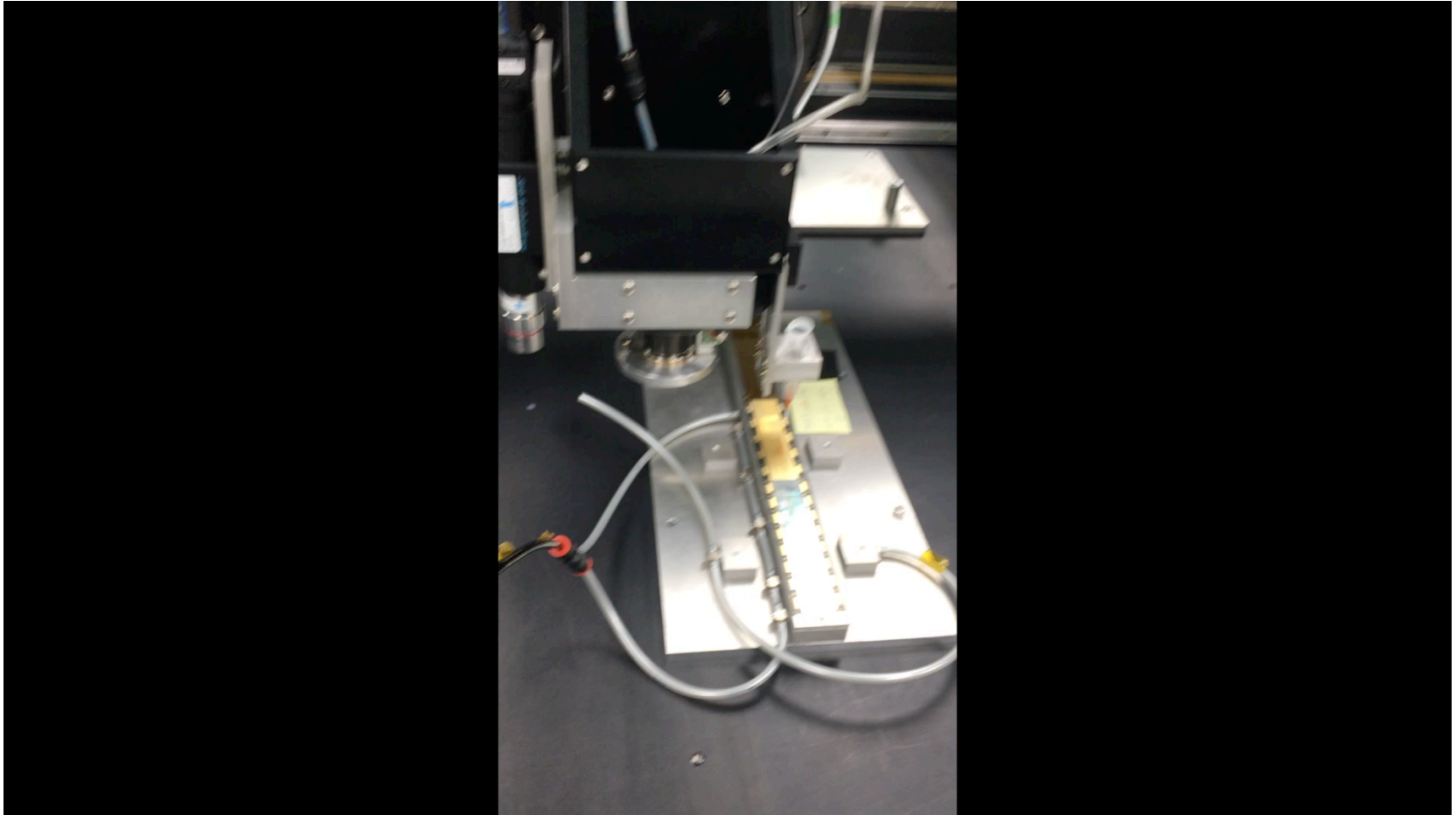


Syringe controlling test



2020/03/24

Gantry control code developed by Rong-Shyang Lu



2020/4/22

Cheng Wei, Shih (NCU HEP, Taiwan)

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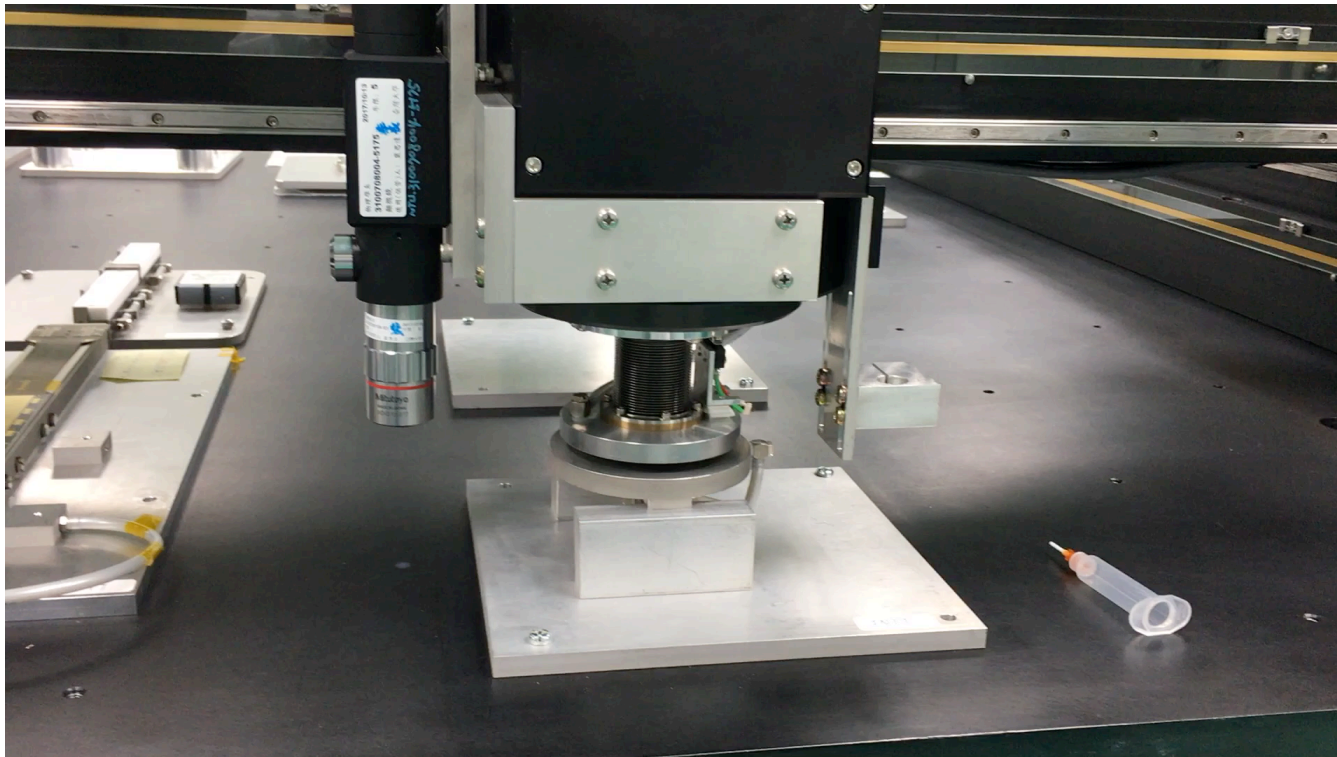


Gantry controlling status



2020/03/24

Gantry control code developed by Rong-Shyang Lu



2020/4/22

Cheng Wei, Shih (NCU HEP, Taiwan)

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